

February 2016

FDT86246L

N-Channel PowerTrench[®] MOSFET 150 V, 2 A, 228 m Ω

Features

- Max $r_{DS(on)}$ = 228 m Ω at V_{GS} = 10 V, I_D = 2 A
- Max $r_{DS(on)}$ = 280 m Ω at V_{GS} = 4.5 V, I_D = 1.8 A
- High performance trench technology for extremely low r_{DS(on)}
- High power and current handling capability in a widely used surface mount package
- Fast switching speed
- 100% UIL Tested
- RoHS Compliant



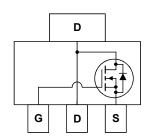
General Description

This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that has been optimized for $r_{DS(on)}$, switching performance and ruggedness.

Applications

- Load Switch
- Primary Switch
- Buck/Boost Switch





MOSFET Maximum Ratings T_C = 25 °C unless otherwise noted

Symbol	F	Parameter		Ratings	Units
V_{DS}	Drain to Source Voltage			150	V
V_{GS}	Gate to Source Voltage			±20	V
	Drain Current -Continuous	T _A = 25 °C	(Note 1a)	2	^
ID	-Pulsed		(Note 4)	20	Α
E _{AS}	Single Pulse Avalanche Energy		(Note 3)	6	mJ
В	Power Dissipation	T _A = 25 °C	(Note 1a)	2.2	W
P_{D}	Power Dissipation	T _A = 25 °C	(Note 1b)	1.0	VV
T _J , T _{STG}	Operating and Storage Junction Te	emperature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	(Note 1)	12	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	(Note 1a)	55	C/VV

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
86246L	FDT86246L	SOT-223	13 "	12 mm	2500 units

Electrical Characteristics T_J = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics					
BV _{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A, V_{GS} = 0 V$	150			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μ A, referenced to 25 °C		110		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 120 V, V _{GS} = 0 V			1	μΑ
I _{GSS}	Gate to Source Leakage Current	V _{GS} = ±20 V, V _{DS} = 0 V			±100	nA

On Characteristics

V _{GS(th)}	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	8.0	1.6	2.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μA, referenced to 25 °C		-5		mV/°C
		V _{GS} = 10 V, I _D = 2 A		189	228	
r _{DS(on)}	()	$V_{GS} = 4.5 \text{ V}, I_D = 1.8 \text{ A}$		208	280	mΩ
		$V_{GS} = 10 \text{ V}, I_D = 2 \text{ A}, T_J = 125 ^{\circ}\text{C}$		375	452	1
9 _{FS}	Forward Transconductance	V _{DS} = 10 V, I _D = 2 A		7.3		S

Dynamic Characteristics

C _{iss}	Input Capacitance	75.77.77		238	335	pF
C _{oss}	Output Capacitance	V _{DS} = 75 V, V _{GS} = 0 V, f = 1 MHz		20	30	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1 101112		2	5	pF
R_{α}	Gate Resistance		0.1	0.9	2.7	Ω

Switching Characteristics

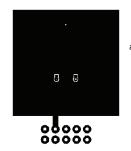
t _{d(on)}	Turn-On Delay Time		4.5	10	ns
t _r	Rise Time	V_{DD} = 75 V, I_{D} = 2 A, V_{GS} = 10 V, R_{GEN} = 6 Ω	1.3	10	ns
t _{d(off)}	Turn-Off Delay Time	V_{GS} = 10 V, R_{GEN} = 6 Ω	11	20	ns
t _f	Fall Time		2	10	ns
$Q_{g(TOT)}$	Total Gate Charge	V _{GS} = 0 V to 10 V	4.5	6.3	nC
$Q_{g(TOT)}$	Total Gate Charge	$V_{GS} = 0 \text{ V to } 4.5 \text{ V}$ $I_{DD} = 75 \text{ V},$ $I_{D} = 2 \text{ A}$	2.3	3.3	nC
Q _{gs}	Total Gate Charge	1 _D - 2 A	0.7		nC
Q_{gd}	Gate to Drain "Miller" Charge		1.0		nC

Drain-Source Diode Characteristics

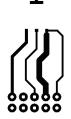
V_{SD}	Source to Drain Diode Forward Voltage	V _{GS} = 0 V, I _S = 2 A	(Note 2)	0.8	1.3	V
t _{rr}	Reverse Recovery Time	I _E = 2 A. di/dt = 100 A/μs		44	71	ns
Q _{rr}	Reverse Recovery Charge	I _F = 2 A, α//αι = 100 A/μs		31	50	nC

NOTES

^{1.} $R_{\theta JA}$ is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5 x 1.5 in. board of FR-4 material. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.



a) 55 °C/W when mounted on a 1 in² pad of 2 oz copper



b) 118 °C/W when mounted on a minimum pad of 2 oz copper

- 2. Pulse Test: Pulse Width < 300 $\mu\text{s},$ Duty cycle < 2.0%.
- 3. E_{AS} of 6 mJ is based on starting T_J = 25 °C; N-ch: L = 3 mH, I_{AS} = 2 A, V_{DD} = 150 V, V_{GS} = 10 V. 100% test at L = 0.1 mH, I_{AS} = 7 A.
- 4. Pulsed Id please refer to Fig 11 SOA graph for more details.
- 5. Computed continuous current limited to Max Junction Temperature only, actual continuous current will be limited by thermal & electro-mechanical application board design.

Typical Characteristics T_J = 25 °C unless otherwise noted.

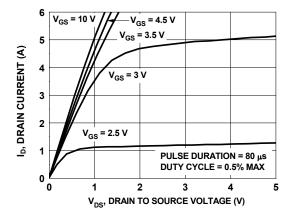


Figure 1. On Region Characteristics

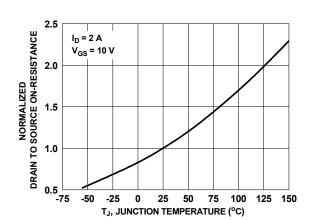


Figure 3. Normalized On Resistance vs. Junction Temperature

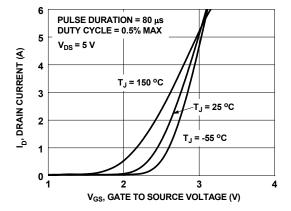


Figure 5. Transfer Characteristics

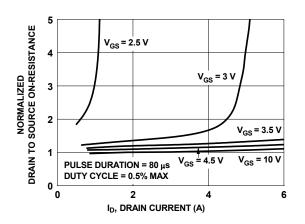


Figure 2. Normalized On-Resistance vs. Drain Current and Gate Voltage

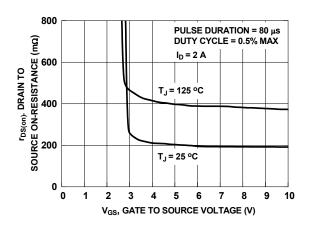


Figure 4. On-Resistance vs. Gate to Source Voltage

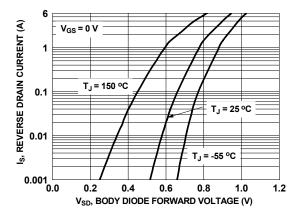


Figure 6. Source to Drain Diode Forward Voltage vs. Source Current

Typical Characteristics T_J = 25 °C unless otherwise noted.

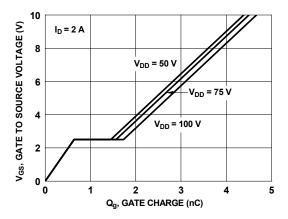


Figure 7. Gate Charge Characteristics

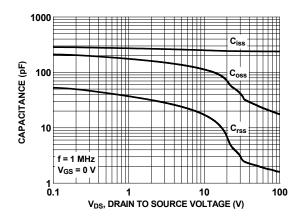


Figure 8. Capacitance vs. Drain to Source Voltage

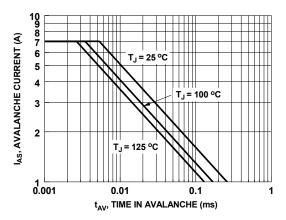


Figure 9. Unclamped Inductive Switching Capability

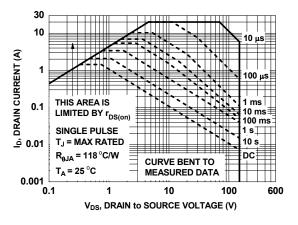


Figure 10. Forward Bias Safe Operating Area

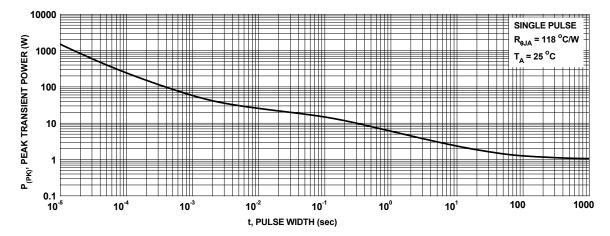


Figure 11. Single Pulse Maximum Power Dissipation

Typical Characteristics $T_J = 25$ °C unless otherwise noted.

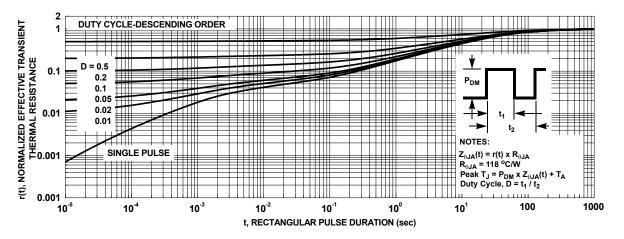
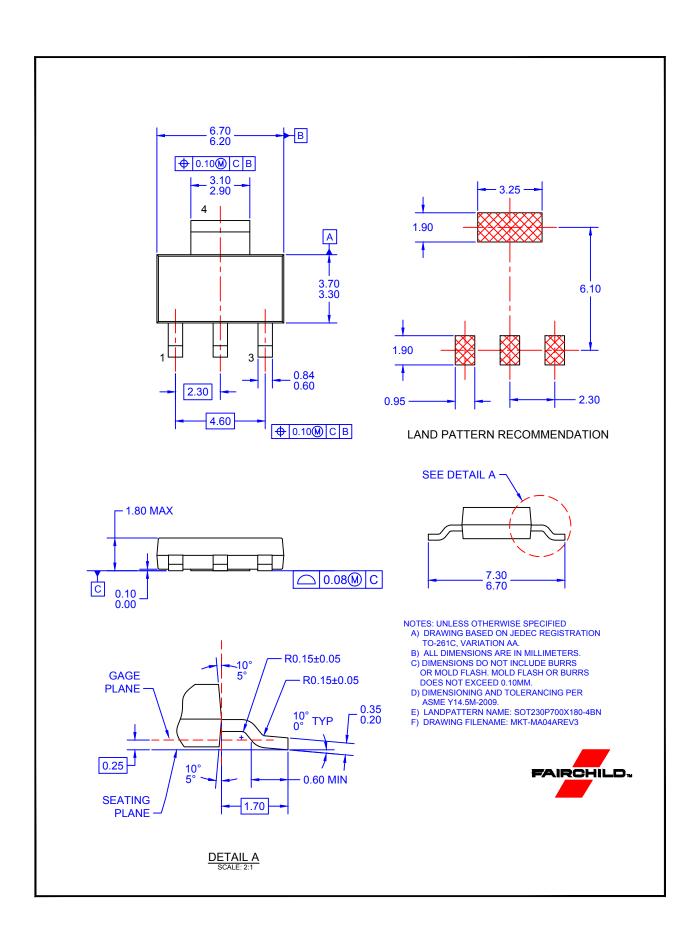


Figure 12. Junction-to-Ambient Transient Thermal Response Curve







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